Kiru Kezuru **Migaku**

Dry Polishing Wheels

# DP08 SERIES

## Chemical-free stress relief dry polishing wheel

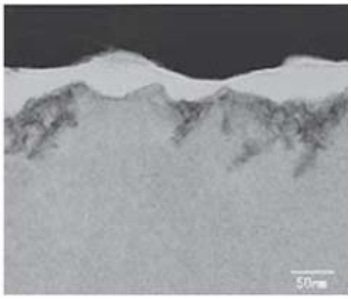
**In addition to wafer polishing in the conventional grinding process, the DP08 realizes chemical-free stress relief that can even be used with the DBG process.**

The DP08 series enables polishing of ultra-thin wafers with DISCO's unique dry polishing process.
In addition to having a low environmental impact by avoiding the use of chemicals, it achieves high die strength and is simple to operate compared to a process that uses slurry.

### ■Damage comparison (Observed with a TEM)

Damage has been removed from the wafer processed with dry polishing.

After DP08 polishing



After #2000 grinding

| Applications |
| --- |
| Silicon wafers, etc. |

# DP08 SERIES

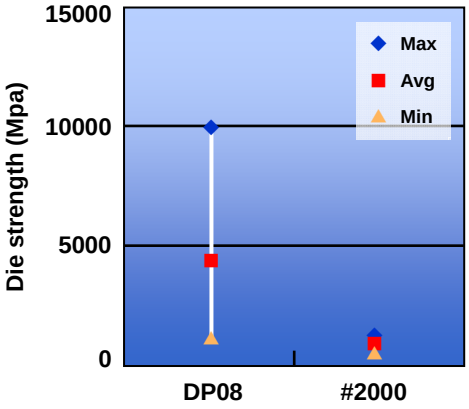
## Specifications

DP08 – BC0101 450 × 11T × 150

| Product type | O.D. | Height | I.D. |
|---|---|---|---|

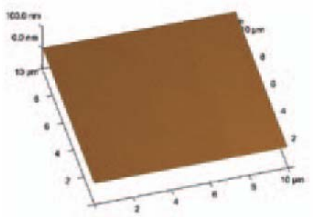
## Experimental Data

### ■Die Strength (Ball point breakage test)

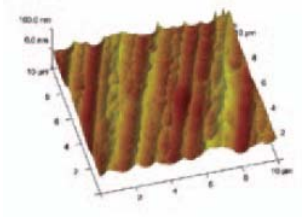



Workpiece : ø8" Silicon wafer
Final grinding thickness : 200 µm

### ■Surface roughness



DP08



Grinding wheel (#2000)

| | DP08 | Grinding wheel (#2000) |
|---|---|---|
| Ra (µm) | 0.0003 | 0.0150 |
| Ry (µm) | 0.0017 | 0.0800 |

**When ordering**

**Please contact a DISCO representative with your product needs such as type, wheel size, and quantity.**

**When you place the first order with us, please explain application information such as materials to grind, sizes, machine, type, and other specification.**

**We are ready to help you to determine which is our most appropriate product type for your application.**

Due to improvements in our products, it is possible that product specifications may be changed without advanced notice.
Please confirm the product specifications with a DISCO representative.

**To use these DISCO blades and wheels (hereafter precision tooling) safely...**
**Please read carefully and follow the instructions below to prevent any accidents or injuries.**

- USE a safety cover (nozzle case, cover), equipped as a standard accessory, to avoid injury.
- DO NOT EXCEED the specified rpm limit indicated on the precision tooling.
- FOLLOW the instruction manual of the equipment to mount the precision tooling properly.
- DO NOT DROP OR HIT the precision tooling. This may cause breakage or injury.
- Always CHECK the precision tooling for chipping or any other damage before starting to use it. DO NOT USE the tooling if there is any damage.
- READ the operation manual of the cutting/grinding equipment before use.
- DO NOT USE the precision tooling with modified or customized equipment.
- DO NOT USE precision tooling that has a different size from the one recommended for your equipment.
- DO NOT USE the precision tooling for any other purpose than grinding, cutting, or polishing.
- Always USE water or coolant to prevent precision tooling damage.